



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APM-SLI/07/2459
Notification Date 04/20/2007

**Cu wire on Ag Spot and Cu wire on Bare Copper Lead
frame in Casablanca for Voltage Regulators**

SLI - LINEAR & INTERFACE

Table 1. Change Identification

Product Identification (Product Family/Commercial Product)	Voltage Regulators assembled in DPAK
Type of change	Package assembly process change
Reason for change	To improve service
Description of the change	Following Divisional commitments towards a capacity improvement and rationalization, Voltage Regulators & Interfaces Business Unit has been decided to add two new assy processes for DPAK package in Casablanca plant: The first process using the Cu wire on Ag spot frame and the second one using the Cu wire on Bare Copper Lead frame. No change in electrical and Quality performances.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Marking on add.info, Cu/Ag:"A"-Cu/Cu:"N"
Manufacturing Location(s)	

Table 2. Change Implementation Schedule

Forecasted implementation date for change	19-Jul-2007
Forecasted availability date of samples for customer	13-Apr-2007
Forecasted date for STMicroelectronics change Qualification Plan results availability	13-Apr-2007
Estimated date of changed product first shipment	20-Jul-2007

DOCUMENT APPROVAL

Name	Function
San biagio, Marcello	Division Marketing Manager
Naso, Lorenzo	Division Product Manager
Lisi, Giuseppe	Division Q.A. Manager



IMS (Industrial & Multisegment Sector)
APM (Analog, Power, MEMS) Group
Voltage Regulator, Interface, Advanced logic & Power RF
Quality & Reliability

Reliability Evaluation Plan and final results
On DPAK Casablanca
Cu wires onto Ag plated L/F

REL-6337-018.07W

Line.. L765
Package. DPAK

Test	Conditions	S.S.	Requirement	Results
PRECONDITIONING OF SMD DEVICES BEFORE TC/THB/PRESSURE POT	DRYNG 1H @ 125°C STORE 168H @ TA=85°C RH=85% IR REFLOW 3 CYCLES @ 260°C+0 -0 °C	231	Parameter within spec. limits at end of preconditionings after go no go test.	No parameter deviation at end of preconditionings.
H.T.S.	TA=150 °C	77 x 1 Lot	Parameter deviation within spec. limits	No parameter deviation at 1000 hours.
T.H.B.	<i>D.U.T. SMD PRECONDITIONED LEVEL 1 JEDEC</i> TA=85°C - RH=85% Vbias=24 V	77 x 1 Lot	Parameter deviation within spec. limits	No parameter deviation at 1000 hours.
H.T.B.	TA=125°C Vbias=35 V	77 x 1 Lot	Parameter deviation within spec. limits	No parameter deviation at 1000 hours.
PRESSURE POT	<i>D.U.T. SMD PRECONDITIONED LEVEL 1 JEDEC</i> TA=121°C - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits	No parameter deviation at 168 hours.
THERMAL CYCLES AIR TO AIR	<i>D.U.T. SMD PRECONDITIONED LEVEL 1 JEDEC</i> TA=-65°C TO 150°C 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits	No parameter deviation at 500 cy
SMD MOISTURE INDUCED STRESS	DRYNG 1H @ 125°C STORE 168H @ TA=85°C RH=85% IR REFLOW 3 CYCLES @ 260°C+0°C -0°C	25 x 1 Lot	Parameter deviation within spec. limits at end of test.	No parameter deviation at end of test.

Present evaluation is valid for all L78M device version

Comments: The reliability tests results are aligned to our STD production



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